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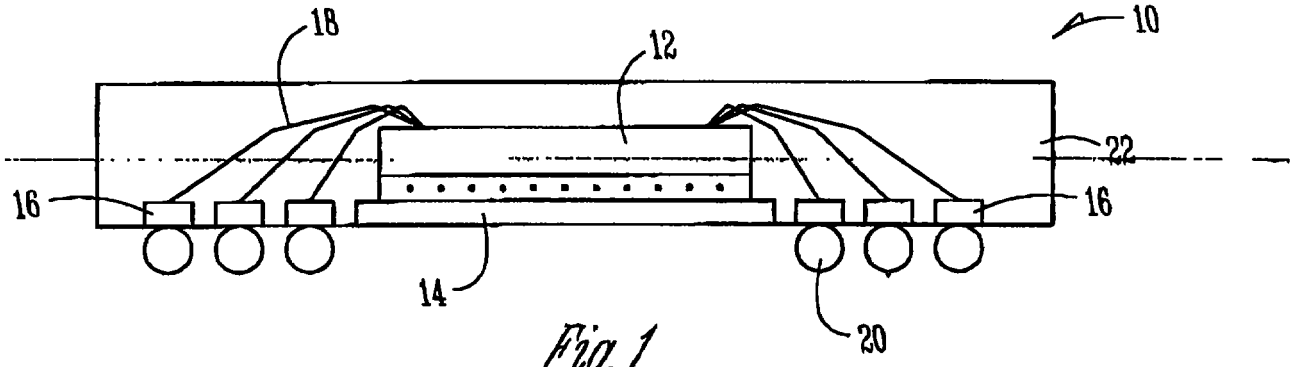


Fig. 1

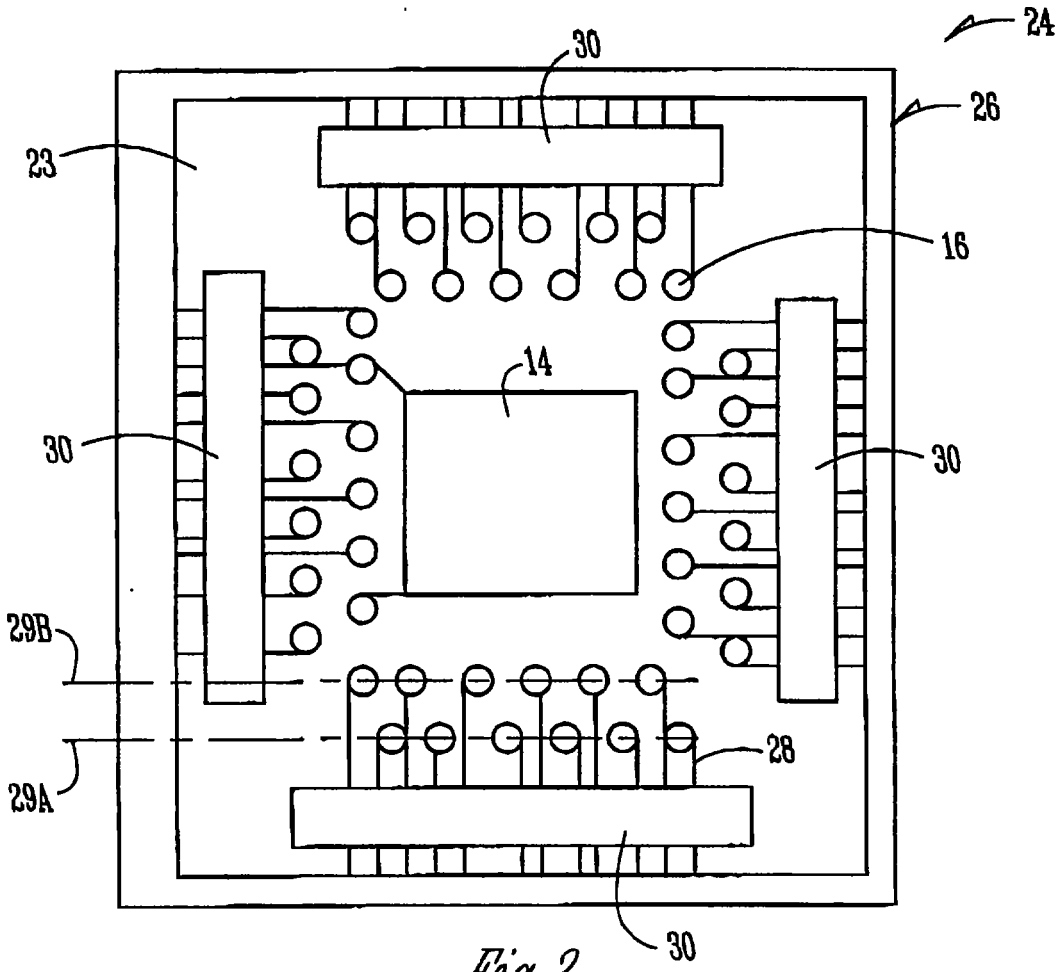


Fig. 2

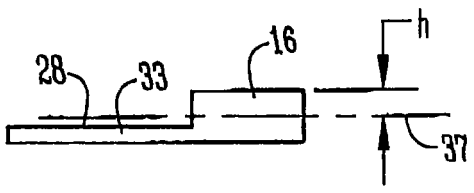


Fig. 3

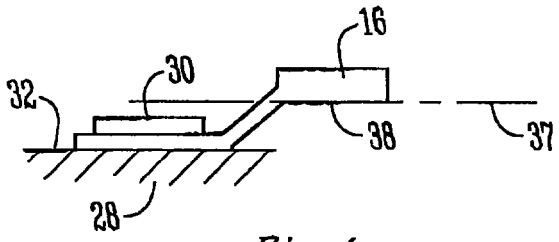


Fig. 4

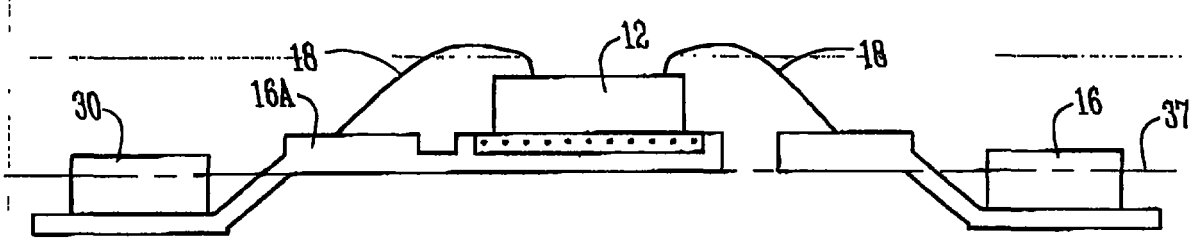


Fig. 5

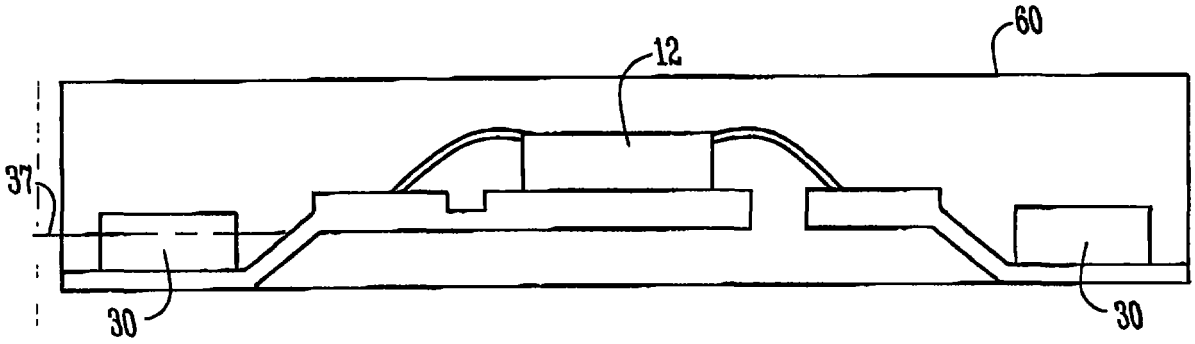


Fig. 6

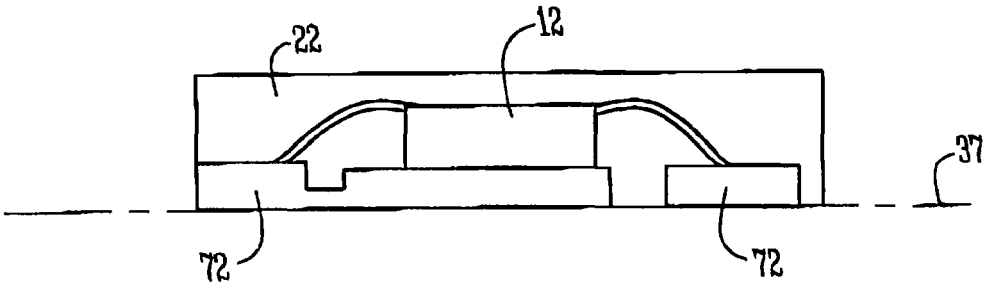


Fig. 7

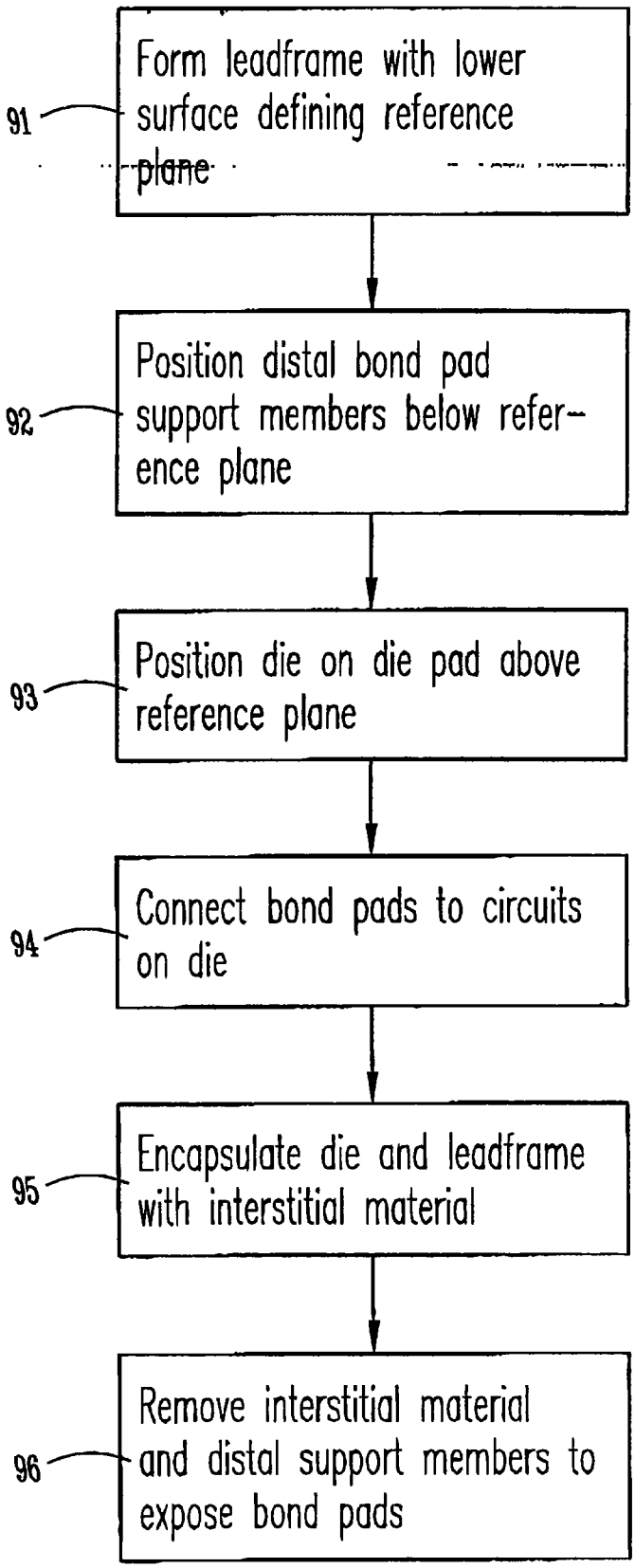

Form leadframe with lower surface defining reference plane
91
Position distal bond pad support members below reference plane
92
Position die on die pad above reference plane
93
Connect bond pads to circuits on die
94
Encapsulate die and leadframe with interstitial material
95
Remove interstitial material and distal support members to expose bond pads
96

Fig. 8